



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPB110N20N3LF	Issued	10. June 2021
MA#	MA001616172		
Package	PG-TO263-3-2	Weight*	1570.48 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	17.615	1.12	1.12	11216	11216
chip_2	inorganic material	silicon	7440-21-3	0.390	0.02	0.02	248	248
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		194	
	non noble metal	copper	7440-50-8	304.026	19.36	19.39	193588	193840
wire	noble metal	gold	7440-57-5	0.066			42	
	non noble metal	aluminium	7429-90-5	13.076	0.83	0.83	8326	8368
encapsulation	inorganic material	zinc oxide	1314-13-2	6.661	0.42		4241	
	miscellaneous	miscellaneous	-	26.645	1.70		16966	
	plastics	epoxy resin	-	99.917	6.36		63622	
	inorganic material	silicon dioxide	60676-86-0	532.893	33.93	42.41	339319	424148
lead finish	non noble metal	tin	7440-31-5	9.657	0.61	0.61	6149	6149
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	145	146
solder	non noble metal	tin	7440-31-5	0.208	0.01		133	
	noble metal	silver	7440-22-4	0.260	0.02		166	
	non noble metal	lead	7439-92-1	9.939	0.63	0.66	6329	6628
glue	plastics	Polyimide	26023-21-2	0.124	0.01	0.01	79	79
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.03		349	
	non noble metal	copper	7440-50-8	547.666	34.90	34.94	348724	349178
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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